

## OPEN PIN FIELD ARRAY SEAM SERIES



Gold on

contact area

Matte Tin on

solder tail

 $= 10\mu$ "

(0,25µm)

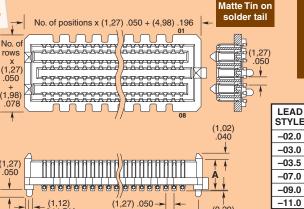
Gold on

contact area

8 8 Fibre Channel 8 Rapid 1/0 8 PCI Express® 8 SATA 8 8 Infiniband Download app notes at 8 www.samtec.com/appnote 8 Contact SIG @ samtec.com 8 8 for questions on protocols 8

MATED HEIGHTS*				
SEAM LEAD STYLE	SEAF LEAD STYLE			
	-05.0	-06.0	-06.5	
-02.0	7mm	8mm	8.5mm	
-03.0	8mm	9mm	9.5mm	
-03.5	8.5mm	9.5mm	10mm	
-07.0	12mm	13mm	13.5mm	
-09.0	14mm	15mm	15.5mm	
-11.0	16mm	17mm	17.5mm	
*Processing conditions will affect mated height.				

Note: Some sizes, styles and options are non-standard. non-returnable.



from

chart

-30, -40, -50

-06 =Six Rows -08 =Eight Rows -10 =Ten Rows

-05

=Five

Rows

Α (4,60) .181 (5,59) .220 (6,10) .240 (9,60) .378 (11,60) .457 **-11.0** (13,60) .535

Tin Alloy 95.5% Sn/3.8% Ag/0.7% Cu Solder Charge

(Required. Arrays will not self-center on solder pads)

= Polyimide film Pick & Place Pad

–TR =Tape & Reel

## DIFFERENTIAL APPLICATION

ARRAY	PAIR COUNT	
50x10	125	
50x8	100	→ (1,27) .050
40x10	100	• • • • •
40x8	80	(1,27) 0 0 0 0 0
40x6	60	
30x10	75	
30x8	60	1 100000
30x6	45	
20x10	50	
20x8	40	
20x10	25	

Due to technical progress, all designs, specifications and components are subject to change without notice.

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(0.20)

No. of positions x (1,27) .050 + (3,58) .141